

What Is Claimed Is:

1 1. A system for integrating circuitry on an isolation
2 layer, comprising:
3 a plurality of isolation substrates, each isolation
4 substrate having a circuit deposition region and a
5 substrate-combining region;
6 a plurality of circuits formed on the circuit deposition
7 regions;
8 a plurality of substrate-connecting elements formed to
9 connect the substrate-combining regions; and
10 a plurality of electrical connecting elements formed to
11 electrically connect the circuits formed on the
12 different circuit deposition regions.

1 2. The system as claimed in claim 1, wherein the
2 substrate-connecting elements are formed by heat fusing or
3 laser.

1 3. The system as claimed in claim 1, wherein the
2 electrical connecting elements are flex print cables or gold
3 lines.

1 4. The system as claimed in claim 1, wherein the
2 electrical connecting elements are formed by laser fusing.

1 5. The system as claimed in claim 1, wherein the
2 materials of the isolation substrates are different.

1 6. The system as claimed in claim 1, wherein the circuit
2 deposition region contacts the substrate-combining region on
3 different planes.

1 7. The system as claimed in claim 1, wherein the
2 materials of the isolation substrates are plastic or glass.

1 8. A method for integrating a system on an isolation
2 layer, comprising the following steps:

3 providing a first isolation substrate including a first
4 circuit deposition region and a first
5 substrate-combining region, and a second isolation
6 substrate including a second circuit deposition
7 region and a second substrate-combining region;

8 forming a first circuit and a second circuit respectively
9 on the first circuit deposition region and the second
10 circuit deposition region;

11 forming a plurality of substrate-connecting elements for
12 connecting the first substrate-combining region to
13 the second substrate-combining region; and

14 forming a plurality of electrical connecting elements to
15 electrically connect the first circuit and the second
16 circuit.

1 9. The method for integrating a system on an isolation
2 layer as claimed in claim 8, wherein the substrate-connecting
3 elements are formed by heat fusing or laser.

1 10. The method for integrating a system on an isolation
2 layer as claimed in claim 8, wherein the electrical connecting
3 elements are flex print cables or gold lines.

1 11. The method for integrating a system on an isolation
2 layer as claimed in claim 8, wherein the electrical connecting
3 elements are formed by laser fusing.

1 12. The method for integrating a system on an isolation
2 layer as claimed in claim 8, wherein the first circuit and the
3 second circuit are packed by different packaging methods.

1 13. The method for integrating a system on an isolation
2 layer as claimed in claim 8, wherein the material of the first
3 isolation substrate and the second isolation substrate is
4 plastic.

1 14. The method for integrating a system on an isolation
2 layer as claimed in claim 8, wherein the material of the first
3 isolation substrate and the second isolation substrate are
4 glass.

1 15. A method for integrating a system on an isolation
2 layer, comprising the following steps:

3 providing a first isolation substrate and a second
4 isolation substrate respectively including a first
5 circuit deposition region and a second circuit
6 deposition region;

7 forming a plurality of first circuits and a plurality of
8 second circuits respectively on the first circuit
9 deposition region and the second circuit deposition
10 region;

11 cutting the first isolation substrate and the second
12 isolation substrate, wherein the cut first isolation
13 substrate comprises single first circuit and a first
14 substrate-combining region, and the cut second
15 isolation substrate comprises a single second
16 circuit and a second substrate-combining region;

17 forming a plurality of substrate-connecting elements for
18 connecting the cut first isolation substrate to the
19 cut second isolation substrate, wherein the first
20 substrate-combining region contacts the second
21 substrate-combining region; and
22 forming a plurality of electrical connecting elements to
23 electrically connect the single first circuit and the
24 single second circuit.

1 16. The method for integrating a system on an isolation
2 layer as claimed in claim 15, wherein the substrate-connecting
3 elements are formed by heat fusing or laser.

1 17. The method for integrating a system on an isolation
2 layer as claimed in claim 15, wherein the electrical connecting
3 elements are flex print cables or gold lines.

1 18. The method for integrating a system on an isolation
2 layer as claimed in claim 15, wherein the electrical connecting
3 elements are formed by laser fusing.

1 19. The method for integrating a system on an isolation
2 layer as claimed in claim 15, wherein the material of the first
3 isolation substrate is plastic.

1 20. The method for integrating a system on an isolation
2 layer as claimed in claim 15, wherein the material of the second
3 isolation substrate is glass.